



Final Product Change Notification

202505016F01 : For LPC55(S)3x in HLQFP100 and HTQFP64, TFME Will be Added as a 2nd Source Assembly Site

Note: This notice is NXP Company Proprietary.

Issue Date: Jun 26, 2025 **Effective Date:** Sep 24, 2025

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Management summary

For LPC55(S)3x in HLQFP100 and HTQFP64, TFME will be added as a 2nd source assembly site.

Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input checked="" type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware <input type="checkbox"/> Other				

Notification Overview

Description

For products LPC55(S)3x in HLQFP100 and HTQFP64, TFME will be added as a 2nd source assembly site.

The assembly material (mold compound) also changes. See the attached self qualification report for details.

Reason

Supply continuity.

Identification of Affected Products

Top Side Marking

The assembly site code is located in the last line of the top side marking. See the attached self qualification report for marking details. For the assembly site, S=ATKH. XN=TFME-HQ),

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment Sep 24, 2025

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

No impact to existing data sheet

Disposition of Old Products

Customers may receive product from either ATKH or TFME assembly sites.

Additional information

Self qualification:[view online](#)

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Jul 26, 2025.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name	Tim Camenzind
Position	Quality Manager
e-mail address	Tim.Camenzind@nxp.com

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High Tech Campus, 5656 AG Eindhoven, The Netherlands

